

LISTING OF CLAIMS:

This listing of claims replaces all prior claim versions and listings:

1. (Previously Presented) A solder paste printing method comprising:

a first process for mounting a mask having apertures corresponding to land portions of a printed circuit board, on said printed circuit board at a predetermined position thereof in a state where it is placed in position;

a second process for mounting a solder paste containing therein as a solder material a tin-zinc (Sn-Zn) system solder on said mask and for permitting said solder paste to make rolling from one end of said mask toward the opposite end thereof by means of a squeegee, while maintaining moisture contained in the atmosphere surrounding said solder paste at a value equal to or less than a predetermined value, wherein said squeegee urges said solder paste to make rolling, to thereby fill said solder paste into said apertures; and

a third process for separating said mask away from said printed circuit board, wherein said moisture is equal to or less than 10 g/m^3 .

2. (Canceled)

3. (Canceled)

4. (Previously Presented) A solder paste printing apparatus comprising:

a mask having apertures corresponding to land portions of a printed circuit board;

a squeegee urging a solder paste containing therein as a solder material a tin-zinc (Sn-Zn) system solder and mounted on said mask, which is placed in position at a predetermined position on said printed circuit board to make rolling from one end of said mask toward the opposite end thereof; and

a moisture regulating means for maintaining moisture contained in the atmosphere surrounding said solder paste at a value equal to or less than a predetermined value, wherein said moisture is equal to or less than 10 g/m^3 .

5. (Canceled)

6. (Previously Presented) The solder paste printing method according to claim 1, wherein said atmosphere mainly comprises a nitrogen gas (N_2).

7. (Previously Presented) The solder paste printing apparatus according to claim 4, wherein said atmosphere mainly comprises a nitrogen gas (N_2).

8. (New) The process of claim 1 when the printing time is substantially continuous when the moisture content is about 10 g/m^3 or lower.

9. (New) The process of claim 1 wherein increase in solder paste viscosity is suppressed when moisture content is maintained at about 10 g/m^3 or lower.

10. (New) The process of claim 4 when the printing time is substantially continuous when the moisture content is about 10g/m^3 or lower.

11. (New) The process of claim 4 wherein increase in solder paste viscosity is suppressed when moisture content is maintained at about 10g/m^3 or lower.